

Blockchain for Industry Applications Summit

Registration Here!



Date: 27th Sep 2018 (Thursday)
Time: 9am - 5pm
Venue: HKPC Conference Hall (4/F)

Blockchain Industry Applications

- Traceability & Authentication
- Transactional Record & Ledger
- Enrichment of Consumer Journey
- Smart Contract
- Supply Chain Implementation
- Blockchain with IoT

With overwhelming response and request for Blockchain applications in the industry usage, HKPC is proud to host this "Blockchain for Industry Applications Summit" to demonstrate our latest Blockchain development with the industry players and for sharing their experience and founding.

IBM Blockchain - What will we solve together?

Mr. Gordon Fung, IBM Solution Architect,
Watson and Cloud Platform

Blockchain Platform for Enterprise

Mr. Ryan Chan, Head of Enterprise, Samsung
Electronics H.K. Co. Ltd.

**Data Sharing and Computation in a Secured
and Privacy-Preserving Manner – Mr. Gabriel
Chan, Secretary-General, Hong Kong Blockchain
Society**

Blockchain on AWS Cloud

Mr. Paul Yung, Head of Territory Business
Development- HK and Taiwan, AWS

SME Business Financing Revolution - Mr. Terence
Yeung, Chief Fintech Officer, MoneySQ.com, Head of
Business Development, trustME Chain Co. Ltd.

**Bring Blockchain to every household through
Internet of Things** - Mr. Fred Leung, Founder and
CEO, AnApp Blockchain Technologies Ltd.

Enquiry

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Email: itsec_enq@hkpc.org

Sponsored and Supporting Organisations: (listed in no particular order)

